L Number	Hits		DB	Time stamp
5	102	427/8-10.ccls. not	USPAT;	2003/04/14 12:48
		(430/22,30,311,313,322,330.ccls. and	US-PGPUB;	
		(((spin\$4 or rotat\$3 or centrifug\$6) and	EPO; JPO;	
		(expos\$3 or radiat\$3 or irradiat\$3 or	IBM_TDB	1
		light\$3) and develop\$3) same (resist or		
		photoresist or photosens\$5 or		-
		photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same		
	1	(resist or photoresist or photosens\$5 or		
		photopolymer\$7)) not (430/22,30.ccls. not		
		((((spin\$4 or rotat\$3 or centrifug\$6) and	1	
		(expos\$3 or radiat\$3 or irradiat\$3 or	,	
	•	light\$3) and develop\$3) same (resist or		
		photoresist or photosens\$5 or		
		photopolymer\$7))) and ((etch\$3 or heat\$3		
		or bak\$3 or prebak\$3 or postbak\$3) same		
		(resist or photoresist or photosens\$5 or		]
_		<pre>photopolymer\$7)))</pre>		
6	10	427/8-10.ccls. and (resist or photoresist)	USPAT;	2003/04/14 15:01
		same (nozzle or dispens\$3 or spread\$3 or	US-PGPUB;	
		pip\$3 or eject\$3) near3 (accelerat\$3 or	EPO; JPO; IBM TDB	
7	10	decelerat\$3 or position\$3 or location) 427/8-10.ccls. and (resist or photoresist)	USPAT;	2003/04/14 15:04
,	10	same (nozzle or dispens\$3 or spread\$3 or	US-PGPUB;	2003/04/14 13:04
	1	pip\$3 or eject\$3) same (accelerat\$3 or	EPO; JPO;	
		decelerat\$3 or position\$3 or location) not	IBM TDB	
		(427/8-10.ccls. and (resist or		
ě		photoresist) same (nozzle or dispens\$3 or		
		spread\$3 or pip\$3 or eject\$3) near3		
		(accelerat\$3 or decelerat\$3 or position\$3		
		or location))		
-	1	("20020037462").PN.	USPAT;	2003/01/21 11:31
			US-PGPUB	
-	2	(("6051349") or ("5968691")).PN.	USPAT;	2003/03/31 15:25
	20	//UCE43170H) on /UC457000H) /UC4317COH)	US-PGPUB	2002/04/01 17 47
-	28	(("6541170") or ("6457882") or ("6431769")	USPAT;	2003/04/01 17:47
		or ("6281962") or ("6266125") or ("6221787") or ("5845170") or ("5939130")	US-PGPUB	
		or ("6543080") or ("6492271") or		
		("5879854") or ("6185472") or ("6001461")		
	-	or ("5817174") or ("6436723") or		
		("6431185") or ("6010797") or ("6118280")		
		or ("5485549") or ("6398429") or		
		("5908657") or ("6444029") or ("6033475")		
		or ("6023084") or ("5831300") or		
		("5933726") or ("5933724") or ("5804479")	1	
		or ("5937290")).PN.		2002/04/02 22 22
-	13	((("6541170") or ("6457882") or	USPAT;	2003/04/01 18:32
		("6431769") or ("6281962") or ("6266125")	US-PGPUB	
		or ("6221787") or ("5845170") or ("5939130") or ("6543080") or ("6492271")		
		or ("5879854") or ("6185472") or	1	
		("6001461") or ("5817174") or ("6436723")		
	1	or ("6431185") or ("6010797") or		
		("6118280") or ("5485549") or ("6398429")		
		or ("5908657") or ("6444029") or		
		("6033475") or ("6023084") or ("5831300")		
		or ("5933726") or ("5933724") or		1
		("5804479") or ("5937290")).PN.) and		
		((spin\$4 or rotat\$3 or centrifug\$3) and		
		(expos\$3 or radiat\$3 or irradiat\$3 or		
		light\$3) and develop\$3) same (resist or	!	
		photoresist or photosens\$5 or		
	1.005	photopolymer\$7)	HEDAT.	2003/04/01 18:34
			USPAT;	2003/04/01 10:34
-	1695	///chinch or rotates or contrifuces and	I HG = DC DHD •	i e
-	1695	(((spin\$4 or rotat\$3 or centrifug\$6) and	US-PGPUB;	
_	1695	(expos\$3 or radiat\$3 or irradiat\$3 or	EPO; JPO;	
-	1693		•	

-	1589	(430/22,30,311,313,322,330.ccls. and	USPAT;	2003/04/10 19:46
		(((spin\$4 or rotat\$3 or centrifug\$6) and	US-PGPUB;	
		(expos\$3 or radiat\$3 or irradiat\$3 or	EPO; JPO;	
		light\$3) and develop\$3) same (resist or	IBM TDB	
		photoresist or photosens\$5 or	_	
1		photopolymer\$7))) and ((etch\$3 or heat\$3		
		or bak\$3 or prebak\$3 or postbak\$3) same		
		(resist or photoresist or photosens\$5 or		
		photopolymer\$7))		
-	603		USPAT;	2003/04/10 19:33
		or centrifug\$6) and (expos\$3 or radiat\$3	US-PGPUB;	
		or irradiat\$3 or light\$3) and develop\$3)	EPO; JPO;	
		same (resist or photoresist or photosens\$5	IBM_TDB	
		or photopolymer\$7))) and ((etch\$3 or		
		heat\$3 or bak\$3 or prebak\$3 or postbak\$3)		
		same (resist or photoresist or photosens\$5		
		or photopolymer\$7)))		
-	1283	430/30.ccls. not (430/22,30.ccls. not	USPAT;	2003/04/10 19:38
		((((spin\$4 or rotat\$3 or centrifug\$6) and	US-PGPUB;	
		(expos\$3 or radiat\$3 or irradiat\$3 or	EPO; JPO;	
		light\$3) and develop\$3) same (resist or	IBM_TDB	
		photoresist or photosens\$5 or		
	•	photopolymer\$7))) and ((etch\$3 or heat\$3		
`		or bak\$3 or prebak\$3 or postbak\$3) same		
		(resist or photoresist or photosens\$5 or	į	
	40	photopolymer\$7)))		0000/04/10 10 40
_	40	(430/30.ccls. not (430/22,30.ccls. not	USPAT;	2003/04/10 19:43
		((((spin\$4 or rotat\$3 or centrifug\$6) and	US-PGPUB;	
		(expos\$3 or radiat\$3 or irradiat\$3 or	EPO; JPO;	
	,	light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or	IBM_TDB	
		photopolymer\$7))) and ((etch\$3 or heat\$3		
		or bak\$3 or prebak\$3 or postbak\$3) same		
		(resist or photoresist or photosens\$5 or		
		photopolymer\$7)))) and ((accelerat\$4 or		
		speed\$3 or rotat\$4 or spin\$4) same (resist		
		or photoresist or photosens\$5 or		
		photopolymer\$7) same (nozzle or pipe or		
		spread\$3 or dispens\$3 or flow\$3))		
_	0	l = .	USPAT;	2003/04/12 12:54
	ľ	((((spin\$4 or rotat\$3 or centrifug\$6) and	US-PGPUB;	2000,01,12 12:01
		(expos\$3 or radiat\$3 or irradiat\$3 or	EPO; JPO;	
		light\$3) and develop\$3) same (resist or	IBM TDB	į
		photoresist or photosens\$5 or	_	
		photopolymer\$7))) and ((etch\$3 or heat\$3		
		or bak\$3 or prebak\$3 or postbak\$3) same		
		(resist or photoresist or photosens\$5 or		
		photopolymer\$7)))) and ((accelerat\$4 or		
		speed\$3 or rotat\$4 or spin\$4) same (resist		
		or photoresist or photosens\$5 or		
		photopolymer\$7) same (nozzle or pipe or		
		spread\$3 or dispens\$3 or flow\$3)) not		į
		(430/22,30,311,313,322,330.ccls. and		
		(((spin\$4 or rotat\$3 or centrifug\$6) and		
		(expos\$3 or radiat\$3 or irradiat\$3 or		
		light\$3) and develop\$3) same (resist or		
1		photoresist or photosens\$5 or		
		photopolymer\$7))) and ((etch\$3 or heat\$3		
		or bak\$3 or prebak\$3 or postbak\$3) same		
1		(resist or photoresist or photosens\$5 or		
	L	photopolymer\$7))	L	

5		USPAT;	2003/04/14 12:42
	(430/22,30,311,313,322,330.ccls. and	US-PGPUB;	ľ
•	(((spin\$4 or rotat\$3 or centrifug\$6) and	EPO; JPO;	
	(expos\$3 or radiat\$3 or irradiat\$3 or	IBM TDB	
	light\$3) and develop\$3) same (resist or	_	
	photoresist or photosens\$5 or		
	photopolymer\$7))) and ((etch\$3 or heat\$3	į	
	or bak\$3 or prebak\$3 or postbak\$3) same		
	(resist or photoresist or photosens\$5 or		
	photopolymer\$7)) not (430/22,30.ccls. not		
	light\$3) and develop\$3) same (resist or		
	•		
66	,	USPAT:	2003/04/10 20:02
	fault) same (nozzle or pipe or spread\$3 or	US-PGPUB:	
		1	
		1	
1		USPAT;	2003/04/11 09:53
-		US-PGPUB	
1	"5912054".PN.	USPAT;	2003/04/11 10:22
_		US-PGPUB	
1	("5409538").PN.	USPAT;	2003/04/11 16:07
	•	US-PGPUB	=====================================
	66	<pre>(expos\$3 or radiat\$3 or irradiat\$3 or light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7)) not (430/22,30.ccls. not ((((spin\$4 or rotat\$3 or centrifug\$6) and (expos\$3 or radiat\$3 or irradiat\$3 or light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) (substrate or wafer) near3 (defect or fault) same (nozzle or pipe or spread\$3 or flow\$3 or dispens\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7) 1 "5489337".PN.</pre> "5912054".PN.	(430/22,30,311,313,322,330.ccls. and (((spin\$4 or rotat\$3 or centrifug\$6) and (expos\$3 or radiat\$3 or irradiat\$3 or light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7)) not (430/22,30.ccls. not ((((spin\$4 or rotat\$3 or centrifug\$6) and (expos\$3 or radiat\$3 or irradiat\$3 or light\$3) and develop\$3) same (resist or photoresist or photosens\$5 or photopolymer\$7))) and ((etch\$3 or heat\$3 or bak\$3 or prebak\$3 or postbak\$3) same (resist or photosens\$5 or photopolymer\$7))) 66 (substrate or wafer) near3 (defect or fault) same (nozzle or pipe or spread\$3 or flow\$3 or dispens\$3) same (resist or photopolymer\$7)  1 "5912054".PN.  USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT;